



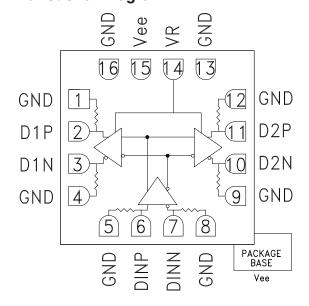
## 28 GBPS, 1:2 FANOUT BUFFER WITH PROGRAMMABLE OUTPUT VOLTAGE

## Typical Applications

The HMC850LC3 is ideal for:

- RF ATE Applications
- · Broadband Test & Measurement
- Serial Data Transmission up to 28 Gbps
- · Clock Buffering up to 20 GHz

## **Functional Diagram**



#### **Features**

Inputs Terminated Internally to 50 Ohms

Differential Inputs are DC Coupled

Propagation Delay: 75 ps

Fast Rise and Fall Times: 16 / 15 ps

Programmable Differential

Output Voltage Swing: 600 - 1100 mV

Power Dissipation: 315 mW

16 Lead Ceramic 3x3 mm SMT Package: 9 mm²

#### **General Description**

The HMC850LC3 is a 1:2 Fanout Buffer designed to support data transmission rates up to 28 Gbps, and clock frequencies as high as 20 GHz. All differential inputs and outputs are DC coupled and terminated on chip with 50 Ohm resistors to the positive supply, ground. The outputs may be used in either single-ended or differential modes, and should be AC or DC coupled into 50 Ohm resistors connected to ground.

The HMC850LC3 also features an output level control pin, VR which allows for loss compensation or for signal level optimization. The HMC850LC3 operates from a single -3.3V DC supply and is available in a ceramic RoHS compliant 3x3 mm SMT package.

## Electrical Specifications, $T_A = +25$ °C, Vee = -3.3 V, VR = 0 V

| Parameter                  | Conditions                 | Min. | Тур.    | Max  | Units |
|----------------------------|----------------------------|------|---------|------|-------|
| Power Supply Voltage       |                            | -3.6 | -3.3    | -3.0 | V     |
| Power Supply Current       |                            |      | 95      |      | mA    |
| Maximum Data Rate          |                            |      | 28      |      | Gbps  |
| Maximum Clock Rate         |                            |      | 20      |      | GHz   |
| Input Voltage Range        |                            | -1.5 |         | 0.5  | V     |
| Input Voltage Differential |                            | 100  |         | 2000 | mV    |
| Input Return Loss          | Frequency <20 GHz          |      | 10      |      | dB    |
| Outros de Auson literal -  | Single-Ended, peak-to-peak |      | 550     |      | mVp-p |
| Output Amplitude           | Differential, peak-to-peak |      | 1100    |      | mVp-p |
| Output High Voltage        |                            |      | -10     |      | mV    |
| Output Low Voltage         |                            |      | -550    |      | mV    |
| Output Rise / Fall Time    | Single-Ended, 20% - 80%    |      | 16 / 15 |      | ps    |





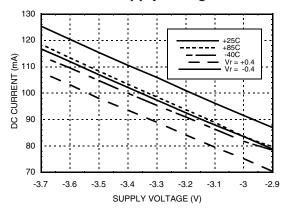
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### **Electrical Specifications** (continued)

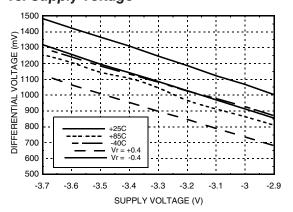
| Parameter                             | Conditions   | Min. | Тур. | Max | Units  |
|---------------------------------------|--|------|------|-----|--------|
| Output Return Loss                    | Frequency <20 GHz  |      | 10   |     | dB     |
| Small Signal Gain                     |  |      | 28   |     | dB     |
| Random Jitter J <sub>R</sub>          | rms  |      | 0.2  |     | ps rms |
| Deterministic Jitter, J <sub>D</sub>  | $\delta$ - $\delta$ , 2 <sup>15</sup> -1 PRBS input <sup>[1]</sup> |      | 2    | 6   | ps     |
| Propagation Delay, td                 |  |      | 75   |     | ps     |
| D1 to D2 Data Skew, t <sub>SKEW</sub> |  |      | 1    | 3   | ps     |

<sup>[1]</sup> Deterministic jitter measured at 13 Gbps with a 300 mVpp, 215-1 PRBS input sequence.

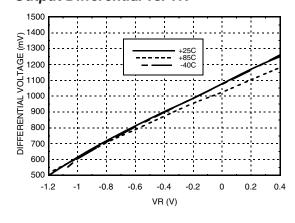
#### DC Current vs. Supply Voltage [1][2]



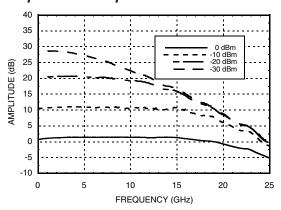
## **Output Differential** vs. Supply Voltage [1][2]



### Output Differential vs. VR [2][4]



### Amplitude vs. Input Power [1][3][4]



[1] VR = 0.0 V

[2] Frequency = 13 Gbps

[3] Device measured on evaluation board with port extensions

[4] Vee = -3.3 V

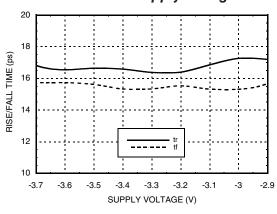
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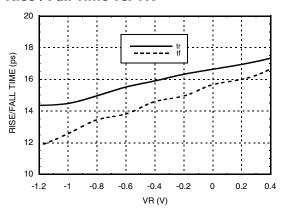


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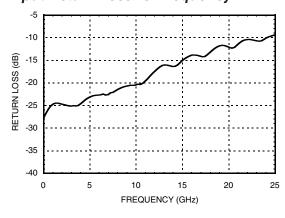
### Rise / Fall Time vs. Supply Voltage [2][4]



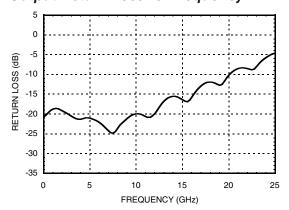
#### Rise / Fall Time vs. VR [2][4]



#### Input Return Loss vs. Frequency [1][3][4]



#### Output Return Loss vs. Frequency [1][3][4]



[1] VR = 0.0 V

[2] Frequency = 13 Gbps

[3] Device measured on evaluation board with port extensions

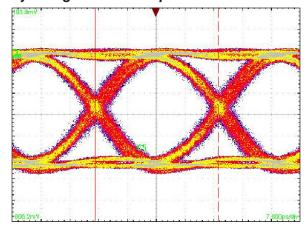
[4] Vee = -3.3 V





## 28 GBPS, 1:2 FANOUT BUFFER WITH PROGRAMMABLE OUTPUT VOLTAGE

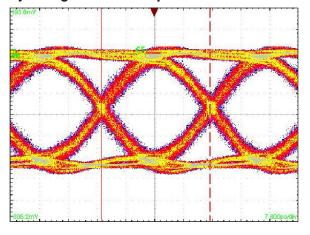
#### Eye Diagram @ 30 Gbps



#### **Test Conditions:**

Single-ended 550 mV data input. Pattern generated with four 2<sup>15</sup> -1 PN patterns applied to the inputs resulting in a Quasi-Periodiic PRBS pattern at 30 Gbps. Measured using Tektronix CSA 8000.

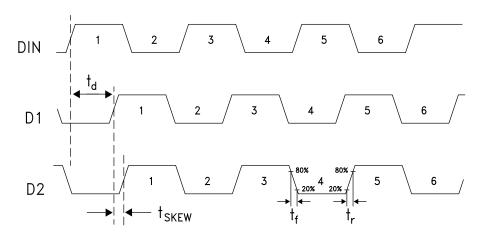
#### Eye Diagram @ 34 Gbps



#### **Test Conditions:**

Single-ended 550 mV data input. Pattern generated with four  $2^{15}$  -1 PN patterns applied to the inputs resulting in a Quasi-Periodiic PRBS pattern at 34 Gbps. Measured using Tektronix CSA 8000.

#### **Timing Diagram**







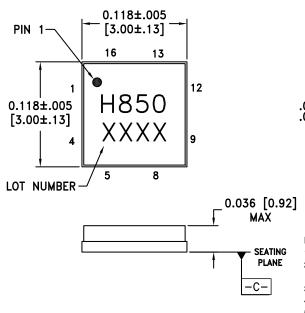
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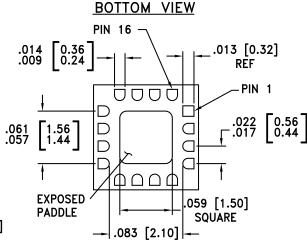
### **Absolute Maximum Ratings**

| Power Supply Voltage (Vee)   | -3.75 V to +0.5 V |
|--|-------------------|
| Input Signals  | -2 V to +0.5 V    |
| Output Signals   | -1.5 V to +0.5 V  |
| Junction Temperature   | 125 °C            |
| Continuous Pdiss (T = 85 °C)<br>(derate 17 mW/°C above 85 °C)                    | 0.68 W            |
| Thermal Resistance (R <sub>th j-p</sub> )<br>Worse case device to package paddle | 59 °C/W           |
| Storage Temperature  | -65 °C to +150 °C |
| Operating Temperature  | -40 °C to +85 °C  |
| ESD Sensitivity (HBM)  | Class 1C          |



### **Outline Drawing**





#### NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING:

30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.

- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C-
- 6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- 7. PADDLE MUST BE SOLDERED TO Vee.

## **Package Information**

| Part Numb | er | Package Body Material | Lead Finish      | MSL Rating | Package Marking [2] |
|-----------|----|-----------------------|------------------|------------|---------------------|
| HMC850L0  | 23 | Alumina, White        | Gold over Nickel | MSL3 [1]   | H850<br>XXXX        |

<sup>[1]</sup> Max peak reflow temperature of 260  $^{\circ}\text{C}$ 

<sup>[2] 4-</sup>Digit lot number XXXX





## 28 GBPS, 1:2 FANOUT BUFFER WITH PROGRAMMABLE OUTPUT VOLTAGE

### **Pin Descriptions**

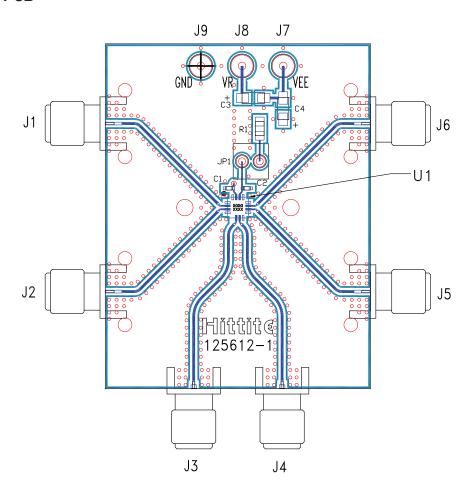
| Pin Number                   | Function              | Description   | Interface Schematic       |  |
|------------------------------|-----------------------|---|---------------------------|--|
| 1, 4, 5, 8, 9,<br>12, 13, 16 | GND                   | These pins must be connected to a high quality RF/DC ground.  | ⊖ GND<br><u>=</u>         |  |
| 2, 3, 10, 11                 | D1P, D1N,<br>D2N, D2P | Differential Data Outputs: Current Mode Logic (CML) referenced to positive supply.  | 50Ω 50Ω DxN               |  |
| 6, 7                         | DINP, DINN            | Differential Data Inputs: Current Mode Logic (CML) referenced to positive supply  | CND<br>50Ω<br>DINP O DINN |  |
| 14                           | VR                    | Output level control. Output level may be increased or decreased by applying a voltage to VR per "Output Differential vs. VR" plot. | VR O                      |  |
| 15<br>Package Base           | Vee                   | These pins and the exposed paddle must be connected to the negative voltage supply.   |                           |  |





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#### **Evaluation PCB**



### List of Materials for Evaluation PCB 125614 [1]

| Item    | Description                 |
|---------|-----------------------------|
| J1 - J6 | PCB Mount K RF Connectors   |
| J7 - J9 | DC Pin                      |
| C1, C2  | 100 pF Capacitor, 0402 Pkg. |
| C3, C4  | 4.7 μF Capacitor, Tantalum  |
| R1      | 10 Ohm Resistor, 0603 Pkg.  |
| U1      | HMC850LC3 Fanout Buffer     |
| PCB [2] | 125612 Evaluation Board     |

<sup>[1]</sup> Reference this number when ordering complete evaluation  $\ensuremath{\mathsf{PCB}}$ 

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed metal package base must be connected to Vee. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. Install jumper on JP1 to short VR to GND for normal operation.

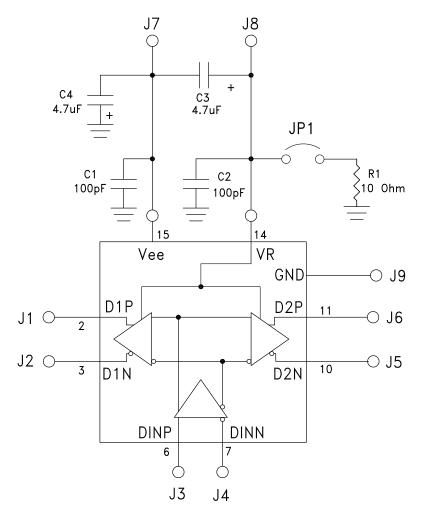
<sup>[2]</sup> Circuit Board Material: Arlon 25FR





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## **Application Circuit**



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HMC850LC3 125614-HMC850LC3 HMC850LC3TR HMC850LC3TR-R5